

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (currently amended) A solder for use in soldering to a surface coated with nickel by electroless plating with a phosphorus-containing plating solution, ~~comprising~~ consisting of 60 - 64 mass % of Sn, 0.002 - 0.01 mass % of P, 0.04 - 0.3 mass % of Cu, and a remainder of Pb.
2. (original) A solder as claimed in claim 1 which is in the form of a solder ball, a solder paste, preformed solder, wire solder, or flux-cored wire solder.
3. (original) A soldering method comprising soldering the solder claimed in claim 1 to a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
4. (original) A soldered joint comprising the solder claimed in claim 1 formed on a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.
5. (original) A method of forming a solder bump comprising heating a solder ball comprising the solder claimed in claim 1 on

a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.

6. (original) A solder bump comprising the solder claimed in claim 1 formed on a surface coated with nickel by electroless plating with a phosphorus-containing plating solution.

7. (original) A substrate for a ball grid array package including a plurality of solder bumps comprising the solder claimed in claim 1 disposed on Cu electrode pads coated with nickel by electroless plating with a phosphorus-containing plating solution.

8. (new) A solder as claimed in claim 1 containing 0.004 - 0.008 mass % of P.

9. (new) A solder as claimed in claim 1 containing 0.06 - 0.2 mass % of Cu.